

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

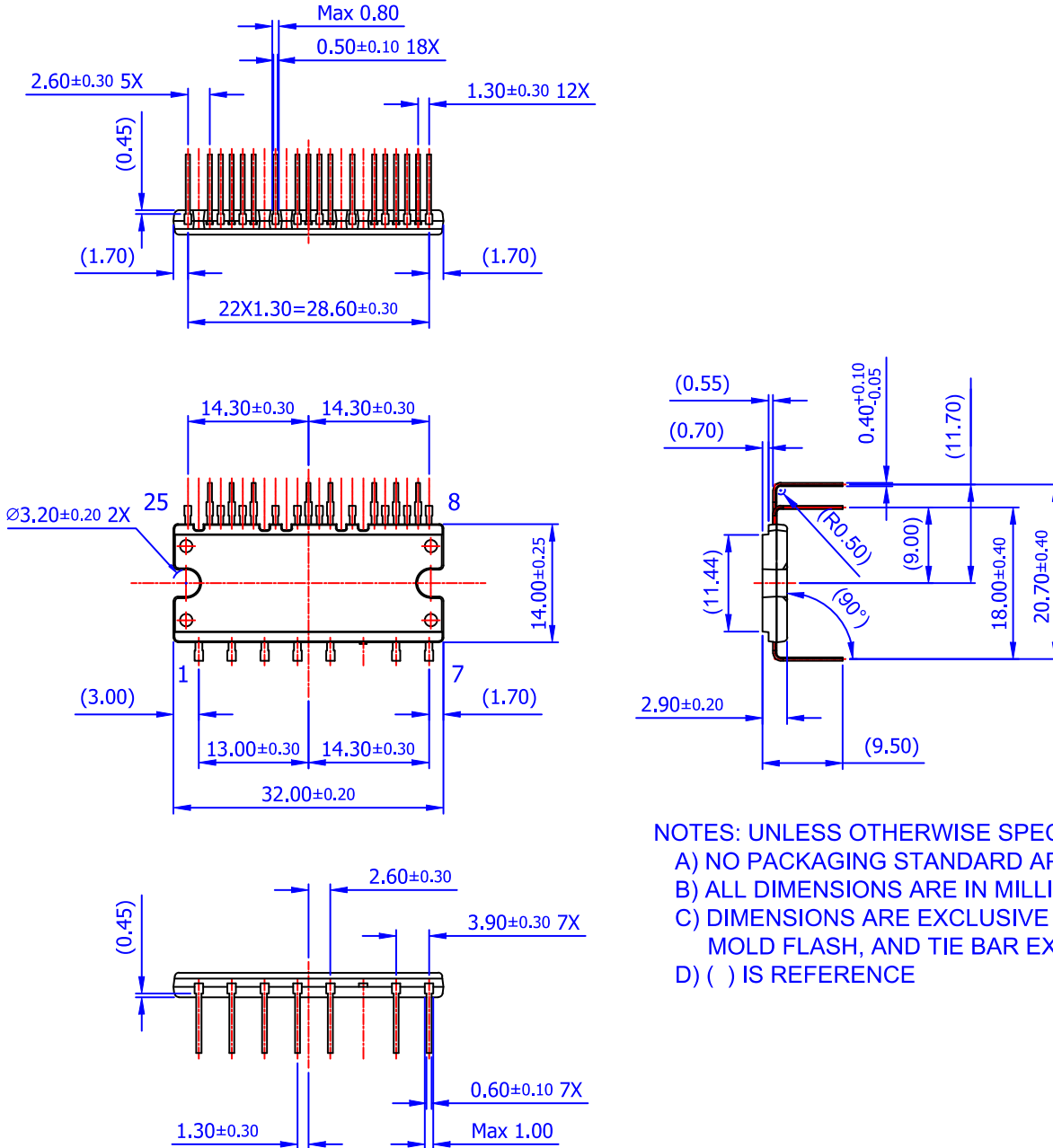
ON Semiconductor®



### SPMFA-A25 / 25LD, FULL PACK, DIP TYPE, SPM8 SERIES

CASE MODEZ  
ISSUE O

DATE 31 JAN 2017



NOTES: UNLESS OTHERWISE SPECIFIED  
 A) NO PACKAGING STANDARD APPLIES  
 B) ALL DIMENSIONS ARE IN MILLIMETERS  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS  
 D) ( ) IS REFERENCE

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